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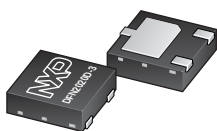
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Kind regards,

Team Nexperia



BC54PAS; BC55PAS; BC56PAS

45V/60V/80V, 1A NPN medium power transistors

Rev. 1 — 11 November 2014

Product data sheet

1. Product profile

1.1 General description

NPN medium power transistor series encapsulated in an ultra thin DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package with medium power capability and visible and solderable side pads.

Table 1. Product overview

Type number ^[1]	Package		PNP complement
BC54PAS	DFN2020D-3	SOT1061D	BC51PAS
BC55PAS			BC52PAS
BC56PAS			BC53PAS

[1] Valid for all available selection groups.

1.2 Features and benefits

- High collector current capability I_C and I_{CM}
- Reduced Printed-Circuit Board (PCB) area requirements
- Exposed heat sink for excellent thermal and electrical conductivity
- AEC-Q101 qualified
- Three current gain selections
- Leadless very small SMD plastic package with medium power capability
- Suitable for Automatic Optical Inspection (AOI) of solder joint

1.3 Applications

- Linear voltage regulators
- Battery driven devices
- MOSFET drivers
- Low-side switches
- Power management
- Amplifiers

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base				
	BC54PAS		-	-	45	V
	BC55PAS		-	-	60	V
	BC56PAS		-	-	80	V
I_C	collector current		-	-	1	A



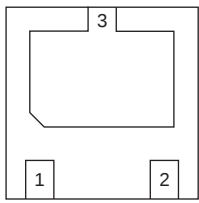
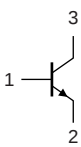
Table 2. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	2	A
h_{FE}	DC current gain	$V_{CE} = 2$ V; $I_C = 150$ mA [1]	63	-	250	
	h_{FE} selection -10	$V_{CE} = 2$ V; $I_C = 150$ mA [1]	63	-	160	
	h_{FE} selection -16	$V_{CE} = 2$ V; $I_C = 150$ mA [1]	100	-	250	

[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base	 Transparent top view	 sym021
2	emitter		
3	collector		

3. Ordering information

Table 4. Ordering information

Type number[1]	Package		
	Name	Description	Version
BC54PAS	DFN2020D-3	DFN2020D-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body $2 \times 2 \times 0.65$ mm.	SOT1061D
BC55PAS			
BC56PAS			

[1] Valid for all available selection groups.

4. Marking

Table 5. Marking codes

Type number	Marking code
BC54PAS	CD
BC54-10PAS	CE
BC54-16-PAS	CF
BC55PAS	CG
BC55-10PAS	CH
BC55-16PAS	CJ
BC56PAS	CK
BC56-10PAS	CL
BC56-16PAS	CM

5. Limiting values

Table 6. Limiting values

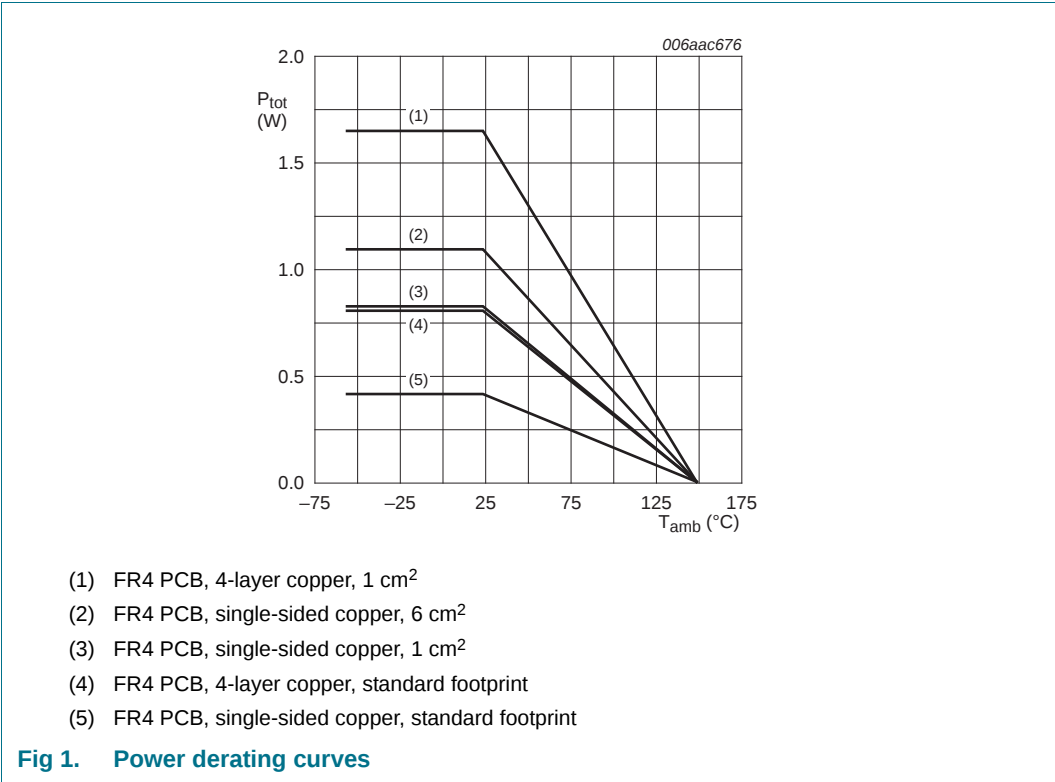
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter			
	BC54PAS		-	45	V
	BC55PAS		-	60	V
	BC56PAS		-	100	V
V_{CEO}	collector-emitter voltage	open base			
	BC54PAS		-	45	V
	BC55PAS		-	60	V
	BC56PAS		-	80	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current		-	1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	2	A
I_B	base current		-	0.3	A

Table 6. **Limiting values ...continued**
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	0.42	W
			[2]	-	0.81	W
			[3]	-	0.83	W
			[4]	-	1.10	W
			[5]	-	1.65	W
T _j	junction temperature		-	150	°C	
T _{amb}	ambient temperature		−55	150	°C	
T _{stg}	storage temperature		−65	150	°C	

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².
- [5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm².

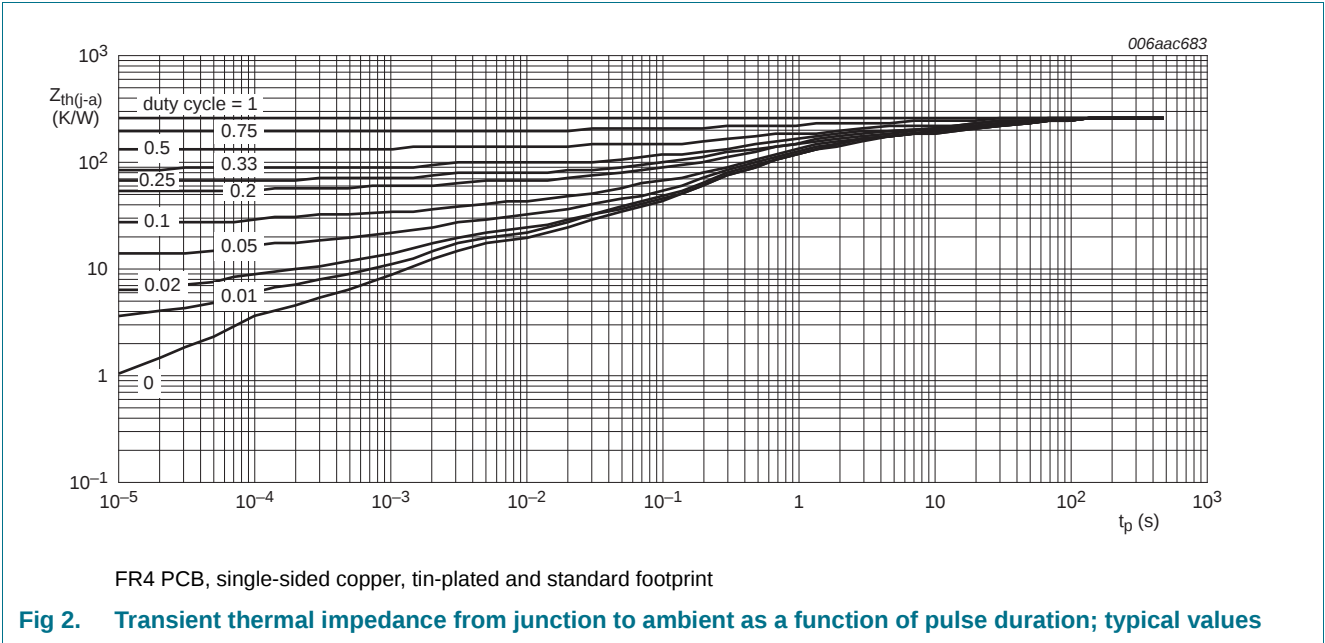


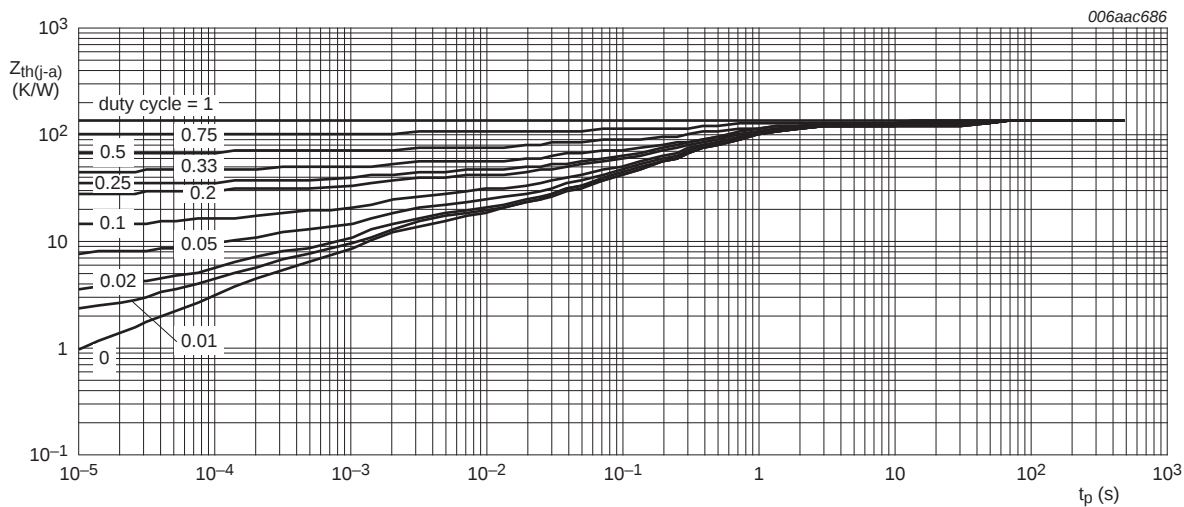
6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] 298	K/W
			[2] 154	K/W
			[3] 151	K/W
			[4] 114	K/W
			[5] 76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point	in free air	20	K/W

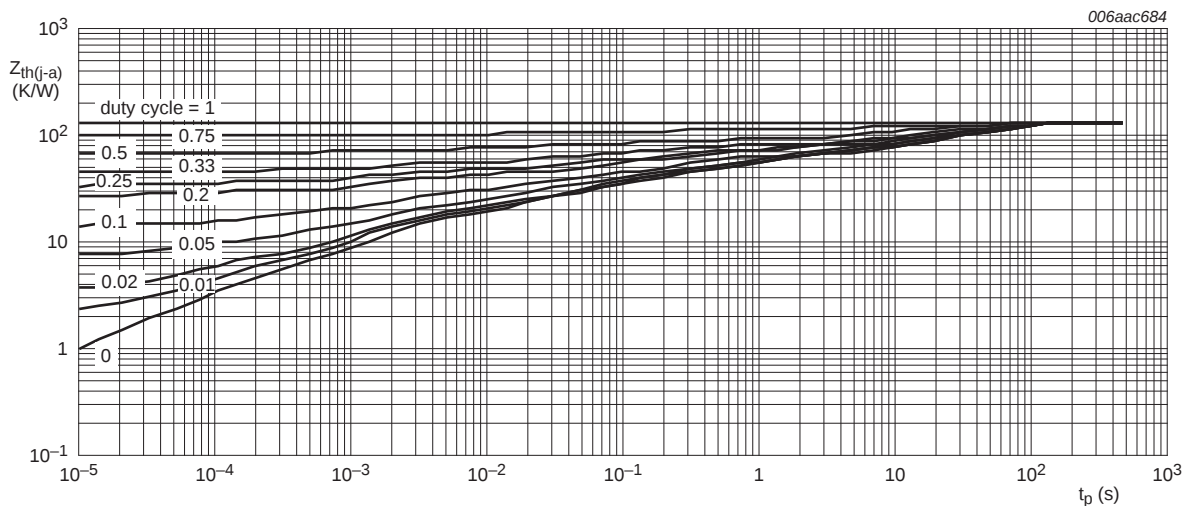
- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².
- [5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm².





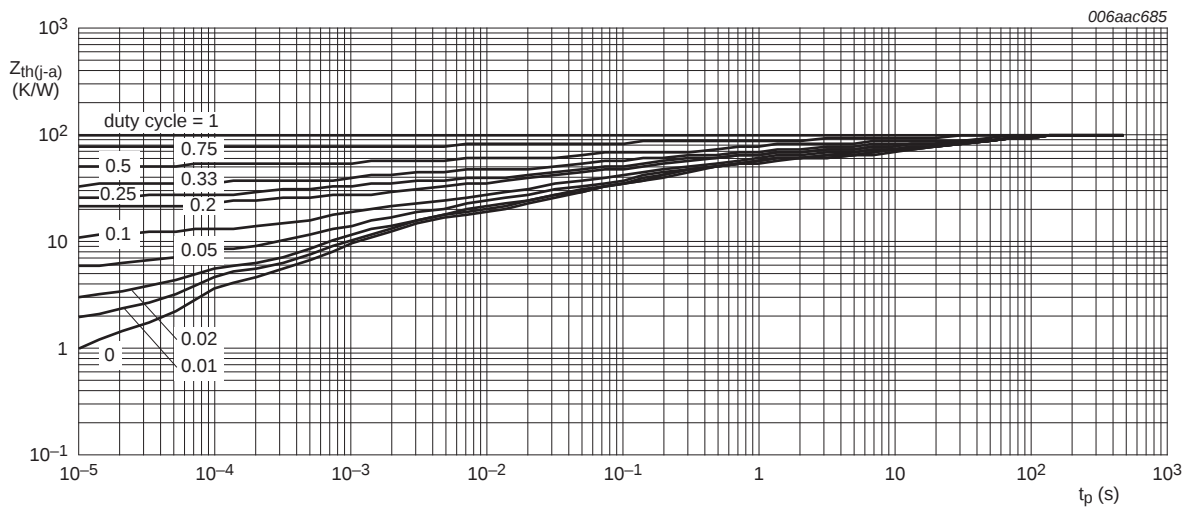
FR4 PCB, 4-layer copper, tin-plated and standard footprint

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



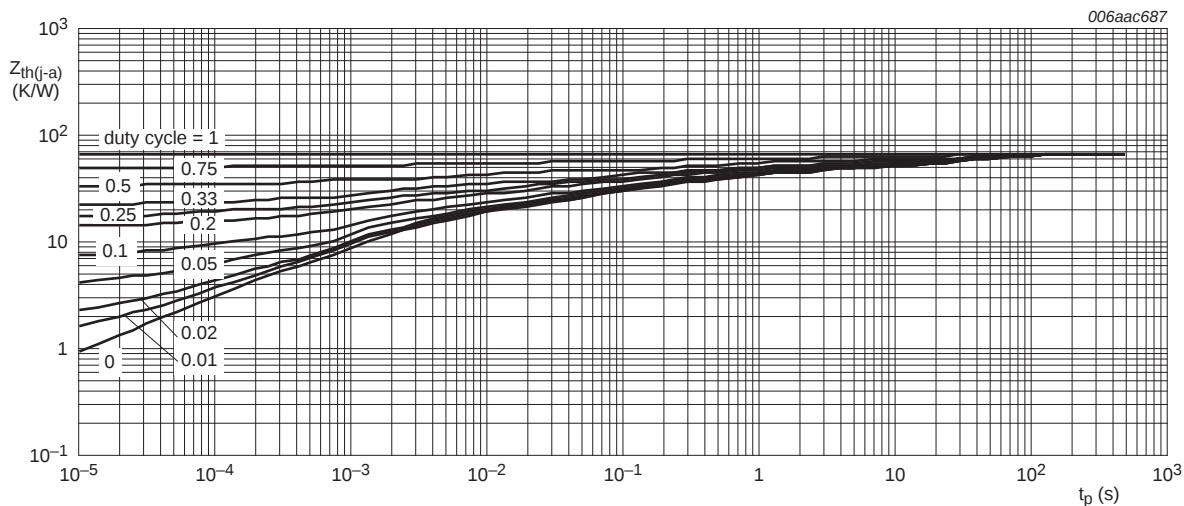
FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm²

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm²

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm²

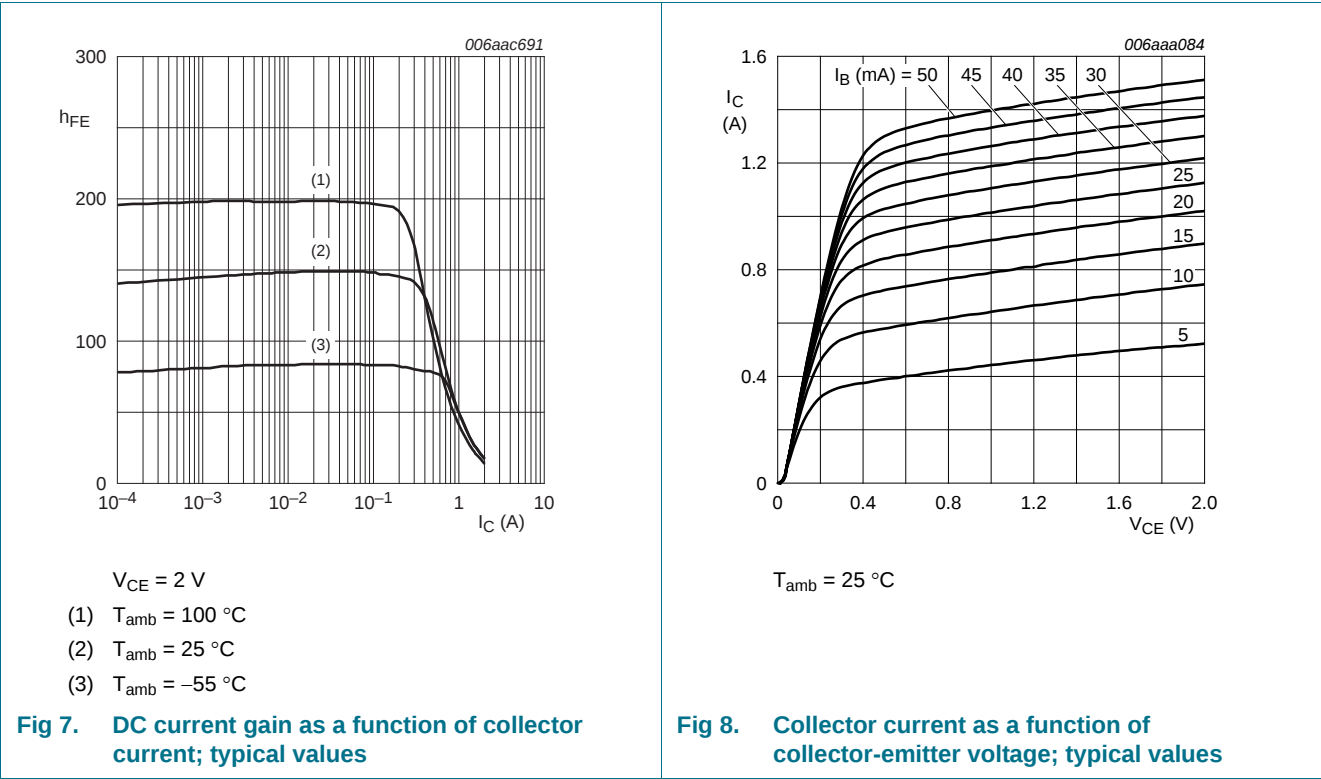
Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

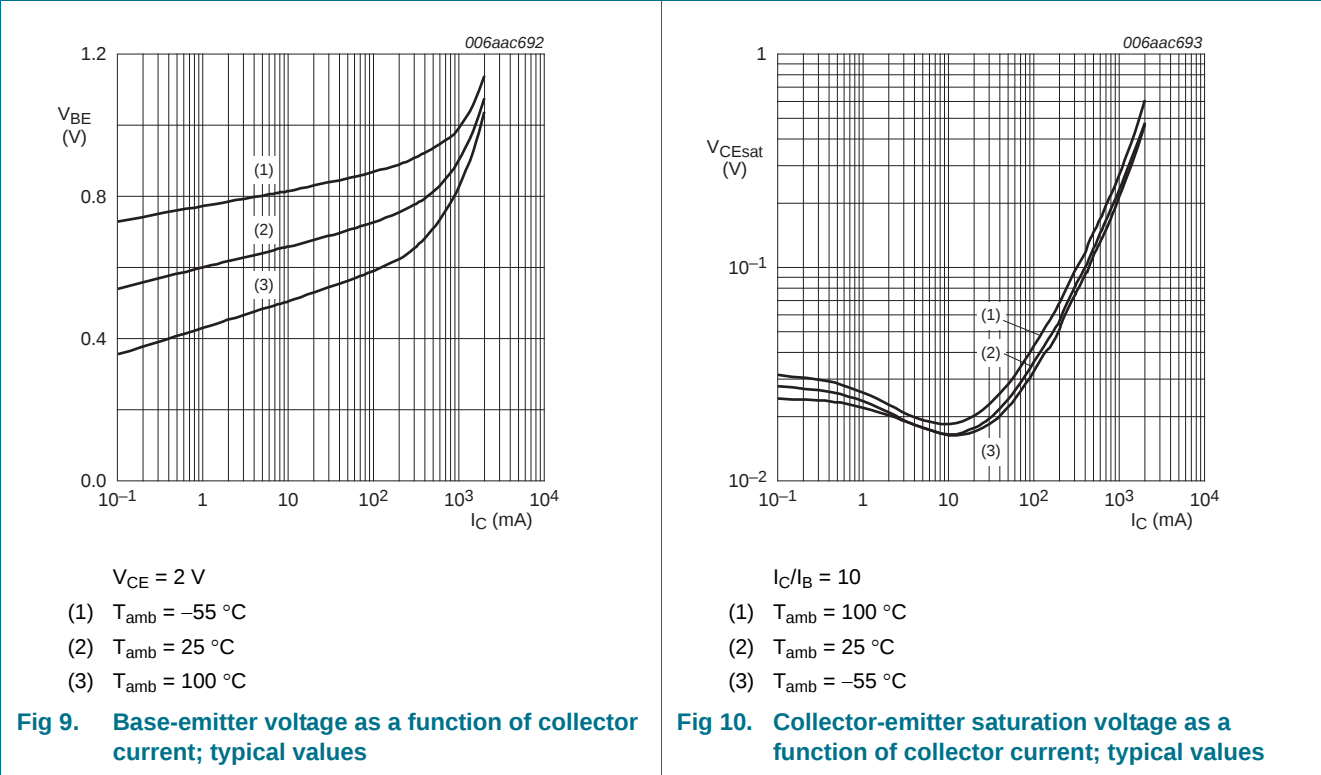
7. Characteristics

Table 8. Characteristics
T_{amb} = 25 °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{CBO}	collector-base cut-off current	V _{CB} = 30 V; I _E = 0 A	-	-	100	nA
		V _{CB} = 30 V; I _E = 0 A; T _J = 150 °C	-	-	10	μA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	-	-	100	nA
h _{FE}	DC current gain	V _{CE} = 2 V; I _C = 5 mA	63	-	-	
		V _{CE} = 2 V; I _C = 150 mA	[1] 63	-	250	
		V _{CE} = 2 V; I _C = 500 mA	[1] 40	-	-	
	h _{FE} selection -10	V _{CE} = 2 V; I _C = 150 mA	[1] 63	-	160	
	h _{FE} selection -16	V _{CE} = 2 V; I _C = 150 mA	[1] 100	-	250	
V _{CEsat}	collector-emitter saturation voltage	I _C = 500 mA; I _B = 50 mA	[1] -	-	500	mV
V _{BE}	base-emitter voltage	V _{CE} = 2 V; I _C = 500 mA	[1] -	-	1	V
C _c	collector capacitance	V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz	-	6	-	pF
f _T	transition frequency	V _{CE} = 5 V; I _C = 50 mA; f = 100 MHz	100	180	-	MHz

[1] Pulse test: t_p ≤ 300 μs; δ ≤ 0.02



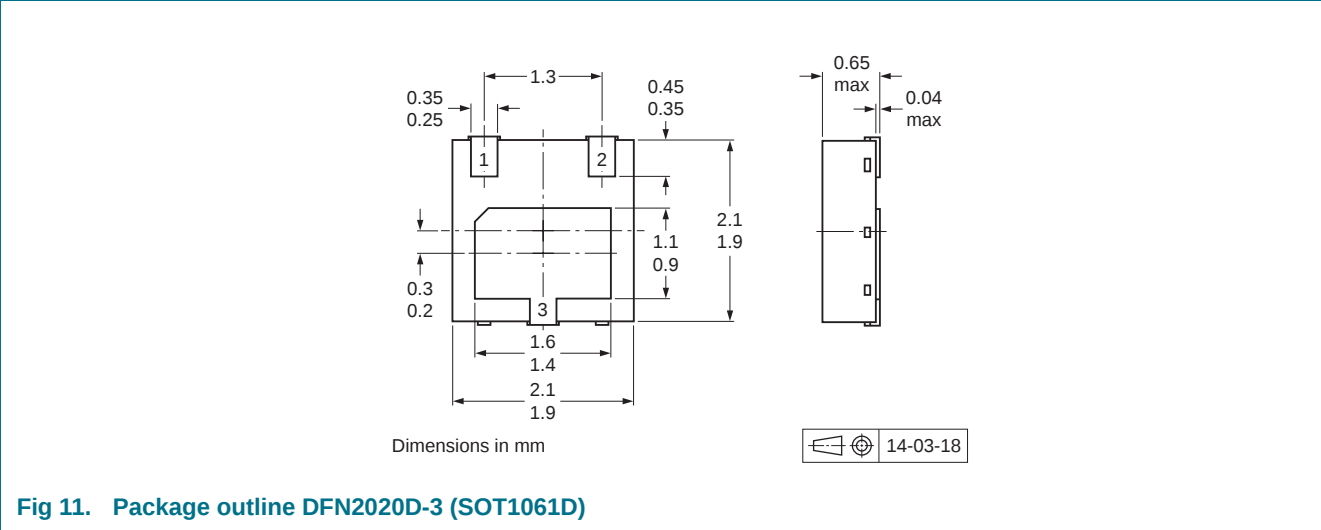


8. Test information

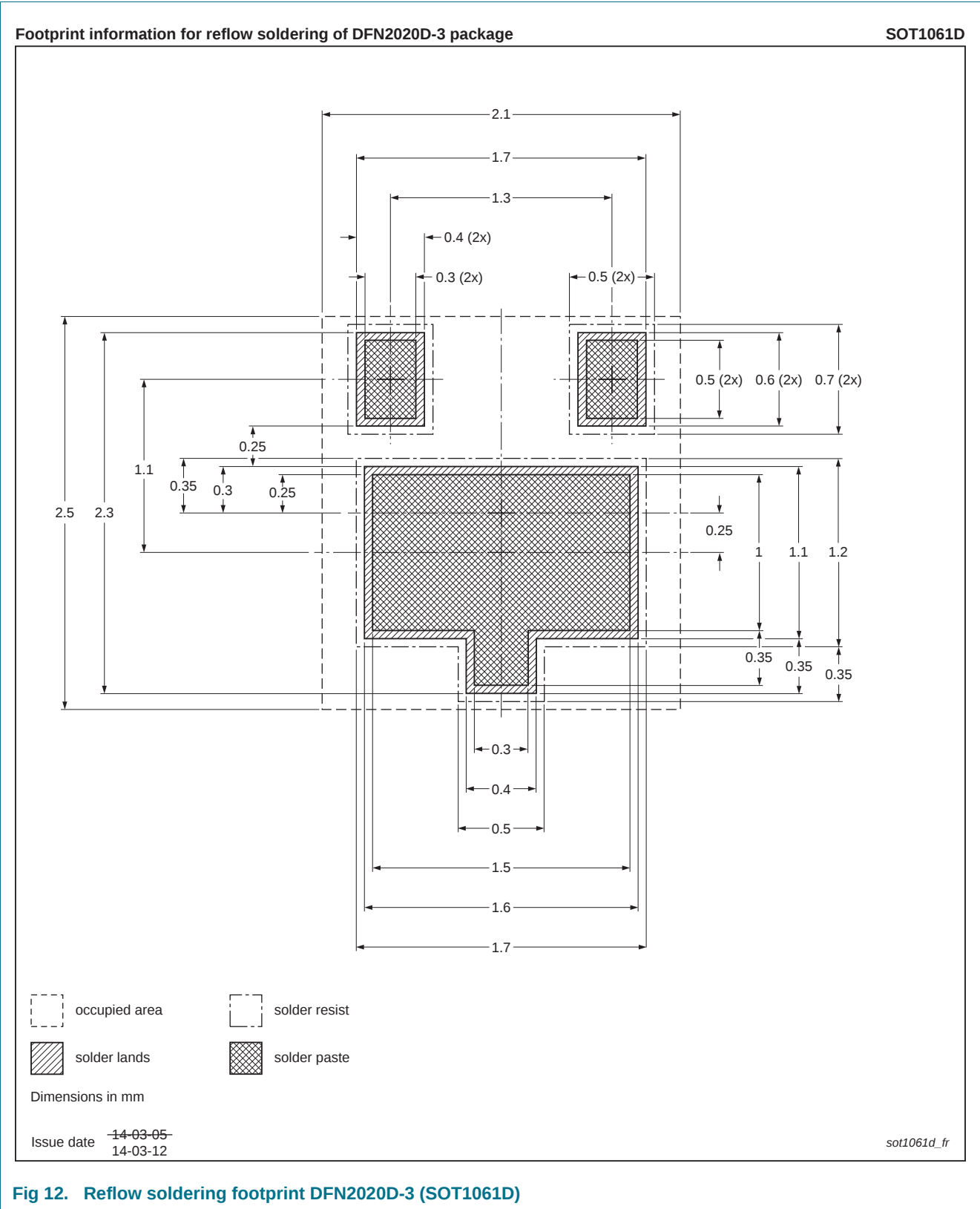
8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline



10. Soldering



11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC54_55_56PAS_SER v.1	20141111	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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14. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	3
5	Limiting values	3
6	Thermal characteristics	5
7	Characteristics	8
8	Test information	9
8.1	Quality information	9
9	Package outline	9
10	Soldering	10
11	Revision history	11
12	Legal information	12
12.1	Data sheet status	12
12.2	Definitions	12
12.3	Disclaimers	12
12.4	Trademarks	13
13	Contact information	13
14	Contents	14

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